

**REMARKS**

Reconsideration and allowance of the above-identified application are respectfully requested. Claims 1, 3 and 5-10 remain pending, wherein claims 1, 8 and 10 are amended.

Claims 1, 3 and 5-8 are rejected under 35 U.S.C. § 112, second paragraph for indefiniteness. This ground of rejection is respectfully traversed.

This rejection is based on the recitation of the high-speed module board and the advance function module board in claim 1. Although it is respectfully submitted that the recitation of these elements in claim 1 is clear and definite, Applicant has amended claim 1 to recite that the multilayer module board is one of (i) a low-end module board, (ii) high-speed module board or (iii) an advanced function module board, and that the base board is connected to one of these boards. Accordingly, it is respectfully submitted that this amendment addresses the issues identified in the Office Action, and this ground of rejection should be withdrawn.

Claims 1 and 5 are rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,477,593 to Khosrowpour et al. ("Khosrowpour"). This ground of rejection is respectfully traversed.

Khosrowpour does not anticipate Applicant's claim 1 because Khosrowpour does not disclose the multilayer module board recited in this claim. In particular, Khosrowpour does not disclose a multilayer module board that includes at least a CPU and a memory. Nor does Khosrowpour disclose a multilayer module board that is one of a low-end module board, a high-speed module board or an advanced function module board.

Khosrowpour discloses a stacked input/output bridge circuit assembly having flexibly configurable connections. Specifically, daughterboards 120 and 130 can be stacked on motherboard 110. (Col. 4, lines 12-13). The daughterboards "may comprise boards employing using through-hole or surface-mounted devices on single or multi-layer printed circuit boards (PCBs), as well as more exotic board structures constructed using, for example, thick-film or co-fired ceramic technologies." (Col. 4, lines 17-21). Khosrowpour does not, however, disclose that daughterboards 120 and 130 include at least a CPU and memory, or that they are one of a low-end module board, a high-speed module board or an advanced function module board.

To reject Applicant's claim 1 the Office Action cites Figure 1 of Khosrowpour. However, Figure 1 of Khosrowpour does not identify the type of components that are included on daughterboards 120 and 130. Nor does Figure

1 of Khosrowpour disclose that these daughterboards are one of a low-end module board, a high-speed module board or an advanced function module board.

Regarding anticipation, M.P.E.P. § 2131, citing *Verdegaal Bros. v. Union Oil Co. of California*, 814 F.2d 628, 631, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987), states that

[a] claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference.

Furthermore, as discussed in M.P.E.P. § 2112, citing *In re Robertson*, 169 F.3d 743, 745, 49 USPQ2d 1949, 1950-51 (Fed. Cir. 1999):

[t]o establish inherency, the extrinsic evidence 'must make clear that the missing descriptive matter is necessarily present in the thing described in the reference, and that it would be so recognized by persons of ordinary skill. Inherency, however, may not be established by probabilities or possibilities. The mere fact that a certain thing may result from a given set of circumstances is not sufficient.'

However, there is nothing in the disclosure of Khosrowpour that expressly or inherently discloses that daughterboards 120 and 130 include at least a CPU and memory, or that they are one of a low-end module board, a high-speed module board or an advanced function module board. Accordingly, Khosrowpour cannot anticipate Applicant's claim 1.

Claim 5 is patentably distinguishable over Khosrowpour at least by virtue of its dependency from claim 1.

For at least those reasons stated above, it is respectfully requested that the rejection of claims 1 and 5 as being anticipated by Khosrowpour be withdrawn.

Claim 3 is rejected under 35 U.S.C. § 103(a) as being obvious in view of the combination of Khosrowpour and U.S. Patent No. 6,085,137 to Aruga et al. ("Aruga"). This ground of rejection is respectfully traversed.

Claim 3 depends from claim 1. As discussed above, Khosrowpour does not disclose all of the elements of Applicant's claim 1. It is respectfully submitted that Aruga does not remedy the above-identified deficiencies of Khosrowpour. Accordingly, the combination of Khosrowpour and Aruga cannot render claim 3, which depends from claim 1, obvious.

For at least those reasons stated above, it is respectfully requested that the rejection of claim 3 as being obvious in view of the combination of Khosrowpour and Aruga be withdrawn.

Claims 6-10 are rejected under 35 U.S.C. § 103(a) as being obvious in view of the combination of Khosrowpour and U.S. Patent No. 5,346,402 to Yasuho et al. ("Yasuho"). This ground of rejection is respectfully traversed.

Claims 6-8 variously depend from claim 1. As discussed above, Khosrowpour does not disclose all of the elements of Applicant's claim 1. It is respectfully submitted that Yasuho does not remedy the above-identified deficiencies of Khosrowpour. Accordingly, the combination of Khosrowpour and Yasuho cannot render claims 6-8, which depend from claim 1, obvious.

Moreover, the combination of Khosrowpour and Yasuho does not disclose or suggest that "the four connector terminals are each carried with the base portion attached to a transfer adapter and the four connector terminals are connected through soldering onto a rear surface of the board while attached to the transfer adapter" as recited in claims 7 and 9.

Independent claims 9 and 10, like claim 1, each recite a multilayer module board that includes a CPU and a memory. Accordingly, for similar reasons to those discussed above with regard to claim 1, the combination of Khosrowpour and Yasuho cannot render these claims obvious.

Furthermore, independent claims 9 and 10 each also recite that "the plurality of high-frequency electronic components are connected with one another through a wiring pattern formed at an inner layer thereof." This claim element is also not disclosed or suggested by the combination of Khosrowpour and Yasuho. It appears that the rejection of these claims relies upon Khosrowpour as disclosing this element. The Office Action, however, does not provide any citations as to where this claim element can be found in Khosrowpour. Accordingly, if this ground of rejection is maintained, Applicant respectfully requests that the next Office Action provide such a citation.

Moreover, claims 8 and 10 each recite a multilayer board module comprising connector terminals each of which include aligning pins projecting at both ends of the base portion to be used when soldering the connector terminal onto a rear surface of the board, and a pair of positioning holes at which the aligning pins are loosely fitted formed at each of the four corners of the board. These elements are not disclosed or suggested by the combination of Khosrowpour and Yasuho.


For at least those reasons stated above, it is respectfully requested that the rejection of claims 6-10 as being obvious in view of the combination of Khosrowpour and Yasuho be withdrawn.

If there are any questions regarding this amendment or the application in general, a telephone call to the undersigned would be appreciated since this should expedite the prosecution of the application for all concerned.

If necessary to effect a timely response, this paper should be considered as a petition for an Extension of Time sufficient to effect a timely response, and please charge any deficiency in fees or credit any overpayments to Deposit Account No. 05-1323 (Docket #029267.55488US).

Respectfully submitted,

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